

LISTING OF THE CLAIMS

Claim 1	currently amended
Claim 2	original
Claim 3	original
Claim 4	currently amended
Claim 5	currently amended
Claim 6	currently amended
Claim 7	currently amended
Claim 8	currently amended
Claim 9	original

TEXT OF CLAIMS CURRENTLY UNDER EXAMINATION

1. (currently amended) A multilayer dicing die bonding film ~~for disposition disposed~~ between a semiconductor silicon wafer and a dicing support tape, the dicing die bonding film comprising
 - (a) Layer-1 adhesive, which ~~comes~~ in contact with the dicing support tape, and
 - (b) Layer-2 adhesive, which ~~comes~~ in contact with the semiconductor silicon wafer, in which the adhesion of Layer-2 to the silicon wafer is higher than the adhesion of Layer-1 to the dicing tape by at least 0.1N/cm.
2. (original) The dicing die bonding film of claim 1 in which the Layer-1 adhesive has a characteristic peel strength to the dicing tape in the range of 0.05 to less than 0.5 N/cm, and the Layer-2 adhesive has a characteristic peel strength to the semiconductor silicon wafer in the range of 0.5 to 10 N/cm.
3. (original) The dicing die bonding film of claim 1 in which the Layer-1 adhesive comprises (a) thermoplastic rubber, (b) thermoset resin having a softening point above 60°C, (c) hardener, (d) accelerator, and (e) filler; and in which the Layer-2 adhesive comprises (a) thermo-plastic rubber, (b) thermoset resin in which at least 20% of the thermoset resin has a softening point below 60°C, (c) hardener, (d) accelerator, and (e) filler.
4. (currently amended) The dicing die bonding film of claim 3 in which the Layer-1 adhesive comprises (a) 30-85 weight % thermoplastic rubber, (b) 15-70 weight % thermoset resin having a softening point above 60°C, (c) 0.05-40 weight % hardener, (d) 0.01-10 weight % accelerator, and (e) 1-~~80~~ 55 weight % filler and the Layer-2 adhesive comprises (a) 30-85 weight % thermoplastic rubber, (b) 15-70 weight % thermoset resin, in which at least 20% of the thermoset resin has a softening point below 60°C, (c) 0.05-40 weight % hardener, (d) 0.01-10 weight % accelerator, and (e) 1-~~80~~ 55 weight % filler.

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5. (currently amended) The dicing die bonding film of claim 4 or claim 4 in which the thermoset resin in Layer-1 is a solid epoxy with a softening point of greater than 60°C and a weight per epoxy equivalent of 100 to 1000.
6. (currently amended) The dicing die bonding film of claim 4 or claim 4 in which the thermoset resin in Layer-2 is an epoxy having a softening point below 60°C and a weight per epoxy equivalent of 100 to 1000.
7. (currently amended) The dicing die bonding film of claim 4 or claim 4 in which the thermoset resin in Layer-2 is a mixture of thermoset resins and at least 20% of the total Layer-2 thermoset resins have a softening point below 60°C.
8. (currently amended) The dicing die bonding film of claim 4 or claim 4 in which the thermoplastic rubber is carboxy terminated butadiene-nitrile/epoxy adduct and nitrile butadiene rubber.
9. (original) The dicing die bonding film of claim 8 in which the carboxy terminated butadiene-nitrile/epoxy adduct consists of about 20-80 wt% carboxy terminated butadiene-nitrile and about 20-80 wt% diglycidyl ether bisphenol A : bisphenol A epoxy.